

IN THE CLAIMS:

Rewrite the pending claims as follows:

1. (Currently Amended) An integrated circuit package, comprising:
a substrate having a top and a bottom, the top including a center region and a peripheral region;
a semiconductor die positioned on the center region of the substrate, the semiconductor die having a bond pad;
a discrete lead finger mounting ring having an inner perimeter positioned on the peripheral region of the substrate and extending upwards therefrom;
a package lead attached to an upper surface of the lead finger mounting ring;
a bond wire with a first end portion bonded to the package lead and a second end portion bonded to the bond pad;
all of a first material comprising an epoxy material confined within the inner perimeter by the lead finger mounting ring and forming a first encapsulation over the bond wire, the semiconductor die, and a portion of the package lead; and
a second material comprising a mold compound forming a second encapsulation over the first encapsulation, the lead finger mounting ring, the top and the bottom of the substrate, and a portion of the package lead.
2. (Original) The package of claim 1, wherein the first encapsulation limits movement of the bond wire during formation of the second encapsulation.
3. (Original) The package of claim 1, further comprising a die attachment pad that is attached between the semiconductor die and the substrate.
4. (Original) The package of claim 1, wherein the lead finger mounting ring comprises non-conductive material.
5. (Original) The package of claim 1, wherein the first protective encapsulation comprises a rounded top surface.
6. (Currently Amended) An integrated circuit package, comprising:

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a substrate having a top and a bottom, the top including a center region and a peripheral region;

a die attachment pad disposed on the center region of the substrate;

a semiconductor die positioned on the die attachment pad, the semiconductor die comprising a plurality of bond pads;

a discrete non-conductive lead finger mounting ring having an inner perimeter positioned on the peripheral region of the substrate and extending upwards therefrom;

a plurality of package leads attached to an upper surface of the lead finger mounting ring;

a plurality of bond wires with first end portions bonded to the package leads and second end portions bonded to the bond pads;

all of a first material comprising an epoxy material confined within the inner perimeter by the lead finger mounting ring and forming a first encapsulation over the bond wires, the first encapsulation having a rounded top surface; and

a second material comprising a mold compound forming a second encapsulation over the first encapsulation, the lead finger mounting ring, and the top and the bottom of the substrate, wherein the first encapsulation limits movement of the bond wires during formation of the second encapsulation.

7. (Original) The package of claim 6, wherein a pad pitch between two of the bond pads is under 60 μm .
8. (Original) The package of claim 7, wherein a length of at least one of the bond wires is at least 3500 μm .
9. (Previously Amended) The package of claim 8, wherein a wire diameter of the at least one bond wire is under 25 μm .

10-17 – Cancelled.